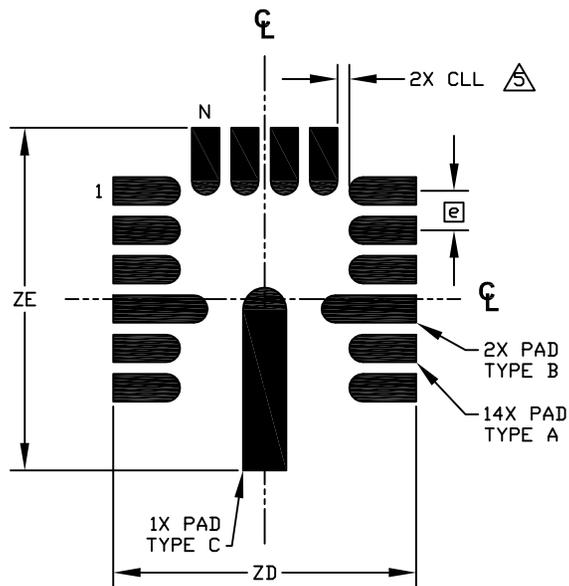
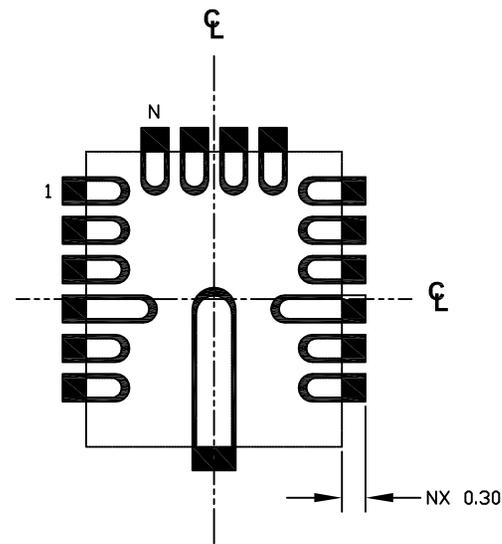


RECOMMENDED LAND PATTERN

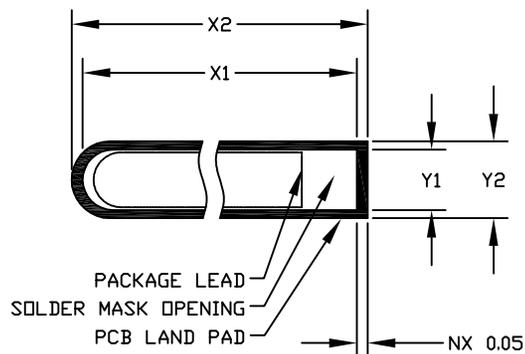


PACKAGE OVERLAY



PACKAGE CODES
[P173A3F+1]
[P173A3F+2]
[P173A3F+3]

PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
CLL	0.15 REF			.006 REF		
e	0.50 BSC			.020 BSC		
N	17 PINS			17 PINS		
ZD	3.85 REF			.152 REF		
ZE	4.35 REF			.171 REF		

DIM	MILLIMETERS			INCHES		
	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.28	0.28	0.48	.011	.011	.019
Y2	0.35	0.35	0.55	.014	.014	.022
X1	0.75	1.10	2.22	.030	.043	.087
X2	0.85	1.20	2.32	.033	.047	.091

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0992 , 21-0993 , 21-0994
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

⚠ CLL IS THE CORNER PAD EDGE TO ADJACENT INSIDE PAD DISTANCE.

-DRAWING NOT TO SCALE-



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.

This document is subject to change without notice.

Contact technical support at <http://www.maximintegrated.com/support> for further questions.

TITLE:  
PACKAGE LAND PATTERN,  
[P173A3F] FCQFN 3.25x3.75x0.95mm

APPROVAL	DOCUMENT CONTROL NO. 90-0496	REV. A	1/1
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